



Pure Copper **CuP - Select**

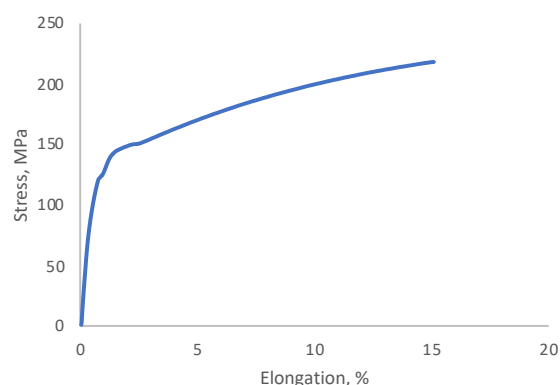
Suggested Applications

Busbars, cable clamps, connectors, heatsinks

Composition %

Cu, min	99.70%
Oxygen, max	0.15%

Tensile Test CuP - Select



Microstructure



SPEE3D heat treated microstructure

Mechanical Properties ¹

	Standard	SPEE3D annealed, xy ³	SPEE3D annealed, z ³	DIN EN 1982 for reference
Conductivity (% IACS)	ASTM E 1004	90	87	94.8
Ultimate Tensile Strength (MPa)	ASTM E8 ²	210	145	150
Elongation at break (%)	ASTM E8 ²	10	N/A	25
Hardness Rockwell B (HRB)	ASTM E18	35		>5
Density (relative) (g/cc)		8.5		8.7

1. Properties shown reflect beta processing parameters. Properties were obtained for annealing loads between 0.2 kg and 3 kg
2. Specimens tested according to ASTM E8 with a modified crosshead displacement rate of insert 0.0025 mm/mm/min.
3. Samples were annealed at 525 °C in air

Listed designations are for reference purposes only. Composition and mechanical properties may vary. End-use material performance is impacted (+/-) by certain factors including but not limited to part geometry and design, application and evaluation conditions.

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